



#### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
001/	45mΩ @ V <sub>GS</sub> = 4.5V	4.5A
20V	55mΩ @ V <sub>GS</sub> = 2.5V	4.1A

## **Description**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## **Applications**

- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors

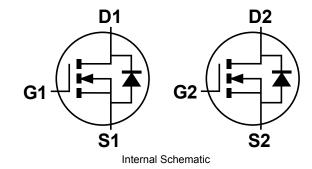
# D2 G2 D1 D1 Pin1 Bottom View

## **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: U-DFN2020-6 Type B
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (approximate)



## Ordering Information (Note 4)

Part Number	Case	Packaging		
DMN2050LFDB -7	DFN2020-6 Type B	3,000/Tape & Reel		
DMN2050LFDB -13	DFN2020-6 Type B	10,000/Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

## **Marking Information**



M5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2009	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Υ	7	Z	Α		В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Drain-Source Voltage		$V_{DSS}$	20	V	
Gate-Source Voltage			$V_{GSS}$	±12	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	l <sub>D</sub>	3.3 2.6	Α
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	Ι <sub>D</sub>	4.5 3.6	А		
Maximum Continuous Body Diode Forward Current	(Note 6)	I <sub>S</sub>	1	Α	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	)	I <sub>DM</sub>	25	Α	
Avalanche Current (Note 7) L = 0.1mH		I <sub>AR</sub>	9	Α	
Repetitive Avalanche Energy (Note 7) L = 0.1mH		E <sub>AR</sub>	4.5	mJ	

## **Thermal Characteristics**

Characteristic	Symbol	Value	Units		
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	Pn	0.73	W	
Total Fower Dissipation (Note 3)	T <sub>A</sub> = +70°C	r <sub>D</sub>	0.46		
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	В	173	°C/W	
Thermal Resistance, sunction to Ambient (Note 5)	t<10s	$R_{ hetaJA}$	110		
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	D	1.42	W	
Total Fower Dissipation (Note 6)	T <sub>A</sub> = +70°C	P <sub>D</sub>	0.90	v v	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	В	89		
Thermal Resistance, Junction to Ambient (Note o)	t<10s	$R_{ hetaJA}$	57	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	18			
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

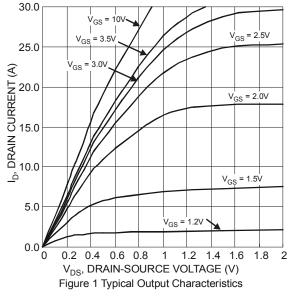
# **Electrical Characteristics** (@T<sub>A</sub> = ±25°C, unless otherwise specified.)

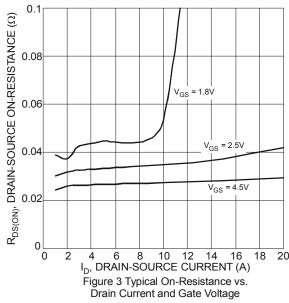
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	-	_	٧	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	-	_	1.0	μΑ	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						•
Gate Threshold Voltage	$V_{GS(th)}$	0.4	_	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance		ı	28	45	mΩ	$V_{GS} = 4.5V$ , $I_D = 5.0A$
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	-	36	55	11177	$V_{GS} = 2.5V$ , $I_D = 4.2A$
Forward Transfer Admittance	Y <sub>fs</sub>	_	9	_	S	$V_{DS} = 5V, I_{D} = 5A$
Diode Forward Voltage	$V_{SD}$	_	0.75	1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C <sub>iss</sub>	ı	389	-	рF	1/ 401/11/ 01/
Output Capacitance	Coss	-	72	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	-	63	_	pF	1 - 1.0WH2
Gate Resistance	Rg	-	2.1	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$	-	5.7	_	nC	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	12	_	nC	
Gate-Source Charge	$Q_{gs}$	-	0.7	_	nC	$V_{DS}$ = 15V, $I_D$ = 5.8A
Gate-Drain Charge	$Q_{gd}$	-	1.5	_	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	-	5	_	ns	
Turn-On Rise Time	t <sub>r</sub>	_	8	_	ns	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 4.5V,
Turn-Off Delay Time	t <sub>D(off)</sub>	_	25	_	ns	$R_G = 6\Omega$ , $I_{DS} = 1A$
Turn-Off Fall Time	t <sub>f</sub>	_	8	_	ns	
Reverse Recovery Time	t <sub>rr</sub>	-	8.5	_	ns	L 54 45/45 400A/c-
Reverse Recovery Charge	Qrr	_	2.1	_	nC	$I_F = 5A$ , di/dt = 100A/ $\mu$ s

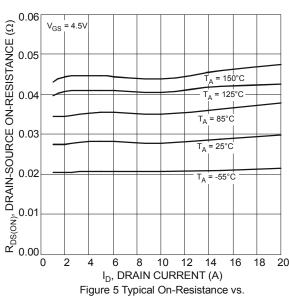
Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7.  $I_{AR}$  and  $E_{AR}$  rating are based on low frequency and duty cycles to keep  $T_J$  = +25°C
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.

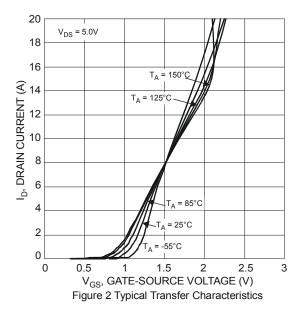


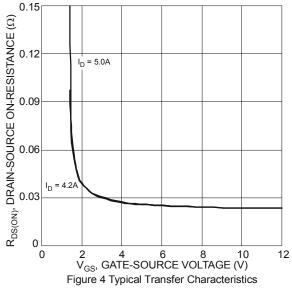






**Drain Current and Temperature** 





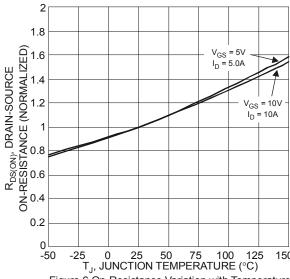


Figure 6 On-Resistance Variation with Temperature



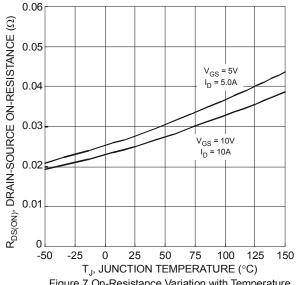
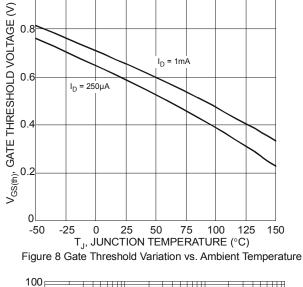
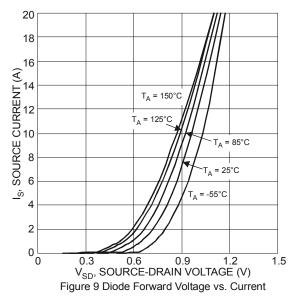


Figure 7 On-Resistance Variation with Temperature





R<sub>DS(on)</sub> -l<sub>p</sub>, DRAIN CURRENT (A) 0.0 1 T<sub>J(max)</sub> = 150°C  $T_A = 25^{\circ}C$ V<sub>GS</sub> = 4.5V Single Pulse
DUT on 1 \* MRP Board 0.01 0.1 10 100 -V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 10 SOA, Safe Operation Area

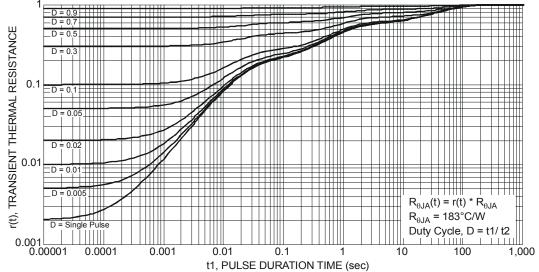
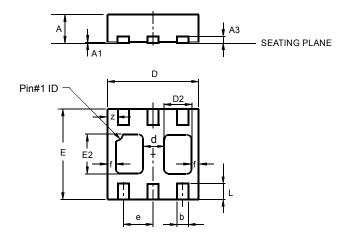


Figure 11 Transient Thermal Resistance



# **Package Outline Dimensions**

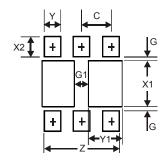
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



DFN2020-6 Type B							
Dim	Min	Max	Тур				
Α	0.545	0.605	0.575				
A1	0	0.05	0.02				
A3		_	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
d		_	0.45				
D2	0.50	0.70	0.60				
е	_	_	0.65				
Е	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
f	_	_	0.15				
L	0.25	0.35	0.30				
Z			0.225				
All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Υ	0.37
Y1	0.70
С	0.65



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